

ABSTRACT OF THE DISCLOSURE

An orthogonal electrical connector using a ball edge array includes one or more stackable fiber optic transceivers, wherein each transceiver includes an electrical substrate, and arrays of solder, which is in form of solder balls or solder paste. The solder is held in predetermined position adjacent to the electrical traces on both sides of the electrical substrate inserted into voids on the molded housing and aligned to contact the electrical traces on the motherboard. The electrical traces on the electrical substrate and the motherboard are located close enough so that the solder physically touches both parts during the soldering process. The solder is reflowed by heat, and the melted solder "wicks up" the electrical traces on the electrical substrate by surface tension.